

### Wire Wound Molded SMD Power Inductors Size 6060

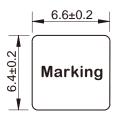
150

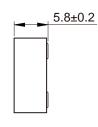
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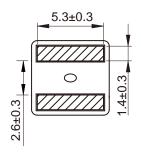
 $^{\circ}$ C

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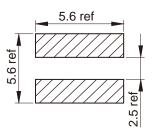
Dimensions: [mm]







# Land Pattern: [mm]



# **Electrical Properties:**

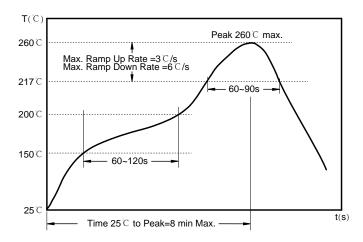
10			

Saturation Current will cause L to drop approximately 30%

Temperature Rise Current: The actual value of DC current when the temperature rise is  $\triangle T$ =40°C



## Soldering Reflow:



Preheat condition: 150 ~200 ℃ / 60~120 sec.

Allowed time above 217 °C: 60~90 sec.

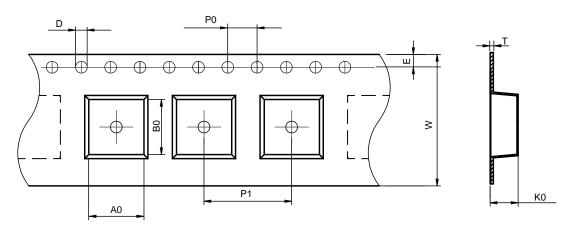
Max temperature: 260℃.

Max time at max temperature: 10 sec.

Allowed Reflow time: 2x max.

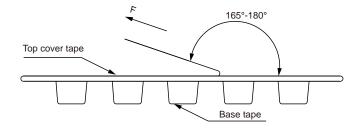
# Packaging Information:

#### Tape Dimension:



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDTE6060	7.0±0.1	6.8±0.1	1.5±0.1	4.0±0.1	12.0±0.1	16.0±0.3	6.3±0.1	1.75±0.1	0.35±0.05

#### Peel force of top cover tape:



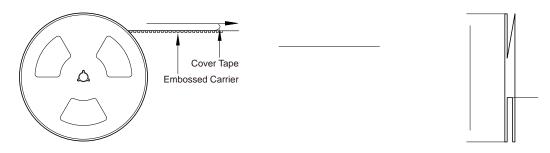
The peel force of top cover tape shall be between 0.1 to 1.3 N

### **Product Marking:**

Marking	Printing (Inductance)



Reel Dimension: [mm]



Packaging Quantity: